Amphenol ICC



Paladin[®] Cabled Backplane

EXTENDING THE REACH OF PASSIVE COPPER IN BACKPLANE, MIDPLANE AND OVERPASS CABLE APPLICATIONS

Cable Backplane Systems is part of Amphenol ICC's Highspeed Backplane Product business, dedicated to developing and manufacturing cabled backplane solutions for next generation system architectures. Our customers are leading providers of datacenter switches and routers, enterprise servers and high performance computers. Products include IO style cables, internal OverPass cables, and full mesh harness structures for both backplane and midplane applications.

- Extends the reach of passive copper for next generation real world system designs; complementary with direct orthogonal designs, intermatable with existing board mount connector designs
- Lowers overall system costs by reducing or eliminating the need for expensive active devices like retimers and high performance board materials
- Market leading backplane connector families Paladin[®]
- Proven reliability of passive twin ax copper coupled with advanced wire attachment and 100% high speed test coverage provides peace of mind
- Turn key support provides mechanical application design services and signal integrity consultation from wire level through system level



- Fully passive copper cable assembly
- Same mechanical benefits as backplane connectors
- Low loss twin ax cable
- Linear transmission beyond 40 GHz
- Flexible pin out
- 32 28 AWG wire gauges
- 100% high speed test coverage
- Mate compatible with press fit headers, right angle and orthogonal configurations



BENEFITS

- Low cost reliable signal transmission
- High pin counts, blind mate & high density
- Overcomes limitation of PCB materials
- Enables 56G NRZ and 110G PAM4 performance
- Allows for full mesh designs with cable harnesses
- Optimization of transmission and cable routing
- Assurance of functional performance
- Line cards / switch cards can be shared between systems allowing for a scalable platform

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Amphenol Information Communications and Commercial Products

TECHNICAL INFORMATION

MATERIAL

- Contacts: High performance Copper Alloy
- Plating(s): Performance-based plating at separable interface (Telcordia GR-1217-CORE)
- Housings: High Performance Thermoplastic, UL94-V0
- Wire: Silver and tin plated copper, polyolefin, aluminized polyester foils

ELECTRICAL PERFORMANCE

- Differential Impedances: 95 Ω
- Supporting all major protocols: IEEE, InfiniBand, OmniPath, UPI, PCIe, SAS

MECHANICAL PERFORMANCE

- Mating wipe: 1.5mm or 2.25mm
- Housing Capture: min 1mm X and Y
- Durability: 250 mating cycles
- Mate and unmate forces equal to press fit connectors

APPROVALS AND CERTIFICATIONS

- Telcordia GR-1217 CORE Central Office
- UL94 V-0
- Twin AX UL HB and VW1

PACKAGING

Product specific

ENVIRONMENTAL

 Operating Temperature Range: -40°C to 85°C connector system

SPECIFICATIONS

TB-2324 Paladin[®] Product Specification

TARGET MARKETS/APPLICATIONS



101010 001000 001100 Switches Routers Access Hubs Wireless Infrastructure

	Server
101010 100010 110011	Datace

Servers Datacenter External Storage System Supercomputers

PART NUMBERS

DESCRIPTION

4X8 Paladin Cable, 30 AWG, 40 GHz
4X8 Paladin Cable, 28 AWG, 40 GHz
4X8 Paladin Cable, 30 AWG, 25 GHz

PART NUMBER

HS30720061	
HS30753261	
HS30780081	

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